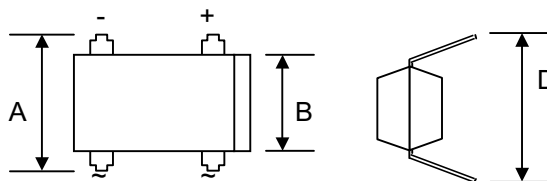


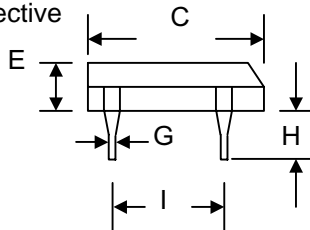
**Features**

- Glass Passivated Die Construction
- Low Forward Voltage Drop
- High Current Capability
- High Surge Current Capability
- Designed for Surface Mount Application
- Plastic Material – UL Recognition Flammability Classification 94V-0
- UL Recognized File # E223064
- Green Products in Compliance with the RoHS Directive



**Mechanical Data**

- Case: Molded Plastic
- Terminals: Plated Leads Solderable per MIL-STD-202, Method 208
- Polarity: As Marked on Case
- Weight: 0.38 grams (approx.)
- Mounting Position: Any
- Marking: Type Number



\*Low profile models (E = 2.20~2.50mm) are available.  
Please consult factory.

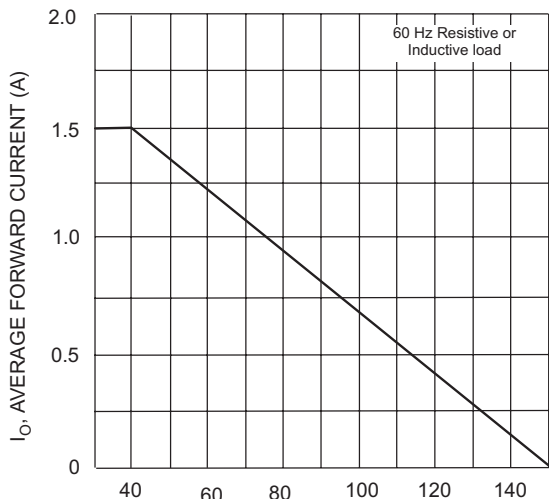
DIL				
Dim	Min	Max	Min	Max
A	7.40	7.90	0.291	0.311
B	6.20	6.50	0.244	0.256
C	8.13	8.51	0.320	0.335
D	7.60	8.90	0.299	0.350
E*	3.20	3.40	0.126	0.134
G	0.41	0.51	0.016	0.020
H	3.90	4.20	0.154	0.165
I	5.0	5.20	0.197	0.205
		In mm		In inch

**Maximum Ratings and Electrical Characteristics** @T<sub>A</sub>=25°C unless otherwise specified

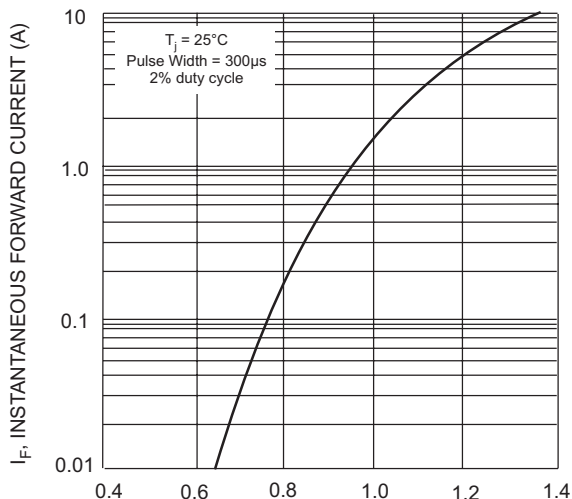
Single Phase, half wave, 60Hz, resistive or inductive load.  
For capacitive load, derate current by 20%.

Characteristic	Symbol	DF150-G	DF151-G	DF152-G	DF154-G	DF156-G	DF158-G	DF1510-G	Unit
Peak Repetitive Reverse Voltage	V <sub>RRM</sub>								
Working Peak Reverse Voltage	V <sub>RWM</sub>	50	100	200	400	600	800	1000	V
DC Blocking Voltage	V <sub>R</sub>								
RMS Reverse Voltage	V <sub>R(RMS)</sub>	35	70	140	280	420	560	700	V
Average Rectified Output Current @T <sub>A</sub> = 40°C	I <sub>o</sub>	1.5							A
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	I <sub>FSM</sub>	50							A
Forward Voltage per element @I <sub>F</sub> = 1.5A	V <sub>FM</sub>	1.1							V
Peak Reverse Current @T <sub>A</sub> = 25°C	I <sub>RM</sub>	10							μA
At Rated DC Blocking Voltage @T <sub>A</sub> = 125°C		500							
Typical Junction Capacitance per element (Note 1)	C <sub>j</sub>	25							pF
Typical Thermal Resistance (Note 2)	R <sub>θJA</sub>	40							K/W
Operating and Storage Temperature Range	T <sub>j</sub> , T <sub>STG</sub>	-55 to +150							°C

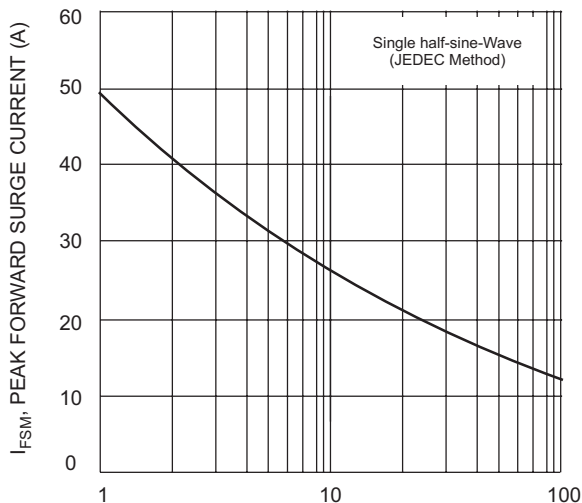
Note: 1. Measured at 1.0 MHz and applied reverse voltage of 4.0V D.C.  
2. Thermal resistance junction to ambient mounted on PC board with 13mm<sup>2</sup> copper pad.



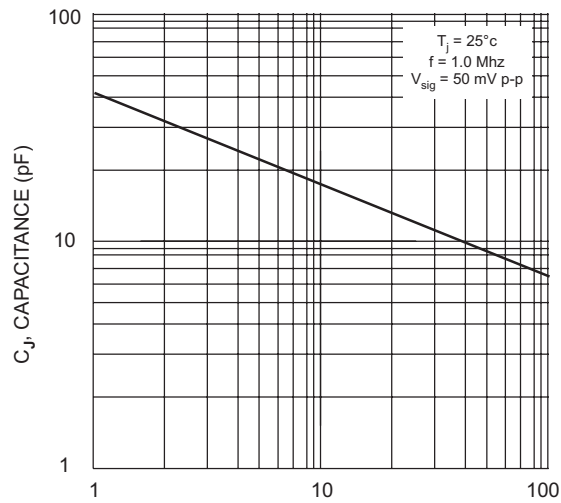
$T_A$ , AMBIENT TEMPERATURE (°C)  
Fig. 1 Output Current Derating Curve



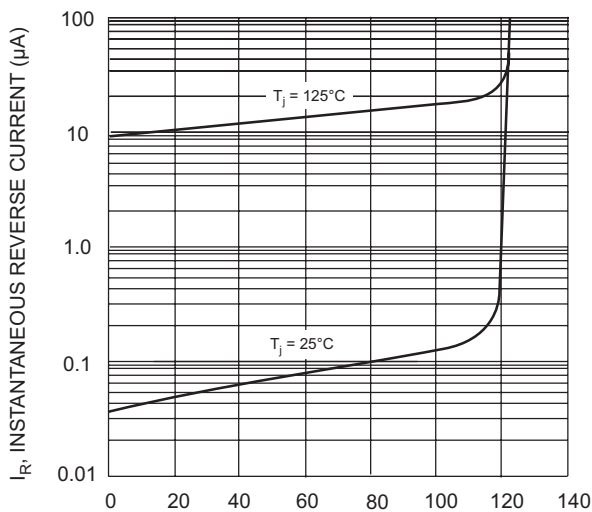
$V_F$ , INSTANTANEOUS FORWARD VOLTAGE (V)  
Fig. 2 Typ Forward Characteristics (per element)



NUMBER OF CYCLES AT 60 Hz  
Fig. 3 Max Non-Repetitive Peak Forward Surge Current



$V_R$ , REVERSE VOLTAGE (V)  
Fig. 4 Typ Junction Capacitance (per element)



PERCENT OF RATED PEAK REVERSE VOLTAGE (%)  
Fig. 5 Typ Reverse Characteristics (per element)

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